APPLICA	BLE STAN	DARD					1				
	VOLTAGE		150V AC cur		CURRENT	RENT 1A					
RATING	OPERATING TEMPERATURE RANGE		-35°C TO + 85°C (NOTI	E 1)	STORAGE TEMPERATURE RANG		-10°C TO + 60°C (I	3)			
	OPERATING HUMIDITY RANGE		40% TO 80% (NOTE 2	2)	STORAGE HUMIDITY RANGE		40% TO 70% (NOT	40% TO 70% (NOTE 3)			
	APPLICABLE CONNECTOR		DF13-10	I	APPLAICABLE CRIMP CONTACT		DF13-2630SCFA, DF13-	-3032	SCFA		
			S-1. 25C								
			SPECIF	ICATI	ONS						
ITEM			TEST METHOD			REQUIREMENTS			АТ		
	RUCTION	Transaction 1				LAGGORDING TO DRAWING					
GENERAL EXAMINATION MARKING		VISUALLY AND BY MEASURING INSTRUMENT. CONFIRMED VISUALLY.			ACCO	ACCORDING TO DRAWING.					
								X	X		
ELECTRIC CHARA CONTACT RESISTANCE					30mΩ	30m $Ω$ MAX.					
INSULATION		100V DC.			500MC	500MΩ MIN.					
RESISTANCE					500IVIC 2	SUUML2 MIN.					
VOLTAGE PROOF		500V AC FOR 1 min.			NO FL	NO FLASHOVER OR BREAKDOWN.					
MECHAN	NICAL CHA	RACTI	ERISTICS		1			1			
MECHANICA		50TIMES INSERTIONS AND EXTRACTIONS.			_	① CONTACT RESISTANCE: $30m\Omega$ MAX.					
OPERATION						② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			-		
VIBRATION						① NO ELECTRICAL DISCONTINUITY OF 1μs.					
		0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			1	② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.					
						1 NO ELECTRICAL DISCONTINUITY OF 1µs.					
						② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.					
ENVIROI	NMENTAL	CHAR	ACTERISTICS			I AICIO.					
RAPID CHA	NGE OF					NTACT RE	SISTANCE: 30mΩ MAX	X			
TEMPERATURE		TIME 30 \rightarrow 5 TO 15 \rightarrow 30 \rightarrow 5 TO 15 min UNDER 5 CYCLES.			3 NO	② INSULATION RESISTANCE: 500MΩ MIN.③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			-		
DAMP HEAT		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			1 -	① CONTACT RESISTANCE: 30mΩ MAX.					
(STEADY STATE)					3 NO	② INSULATION RESISTANCE: 500MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.					
l '		1 '	1) FLOW SOLDERING			NO DEFORMATION OF CASE OF					
SOLDERING HEAT		250±5°CMAX, FOR 3 SECONDS. 2) SOLDERING IRONS: :290±10°C, FOR 3 SECONDS			I	EXCESSIVE LOOSENESS OF THE TERMINALS.					
		+	SOLDERED AT SOLDER TEMPERATURE,			SOLDER SHALL COVER A MINIMUM OF					
		215±5°C FOR INSERTION DURATION, 3 SECONDS.			95 %	95 % OF THE SURFACE BEING IMMERSED.					
REMARKS					<u> </u>				1		
	LUDING THE TOUR CONDENSING		TURE RISE BY CURRENT.								
NOTE3:APP	LY TO THE CO	NDITION	OF LONG TERM STORAGE								
			FTER PCBBOARD , OPERATIN ED FOR INTERM STORAGE DU								
COUN			SCRIPTION OF REVISIONS DESI								
Δ											
Unless otherwise specifid , re			fer to JIS C 5402.			APPROV	ED TS. SAKATA	08. 1	2.04		
					CHECKE	ED TS. KUMAZAWA	08. 12. 03				
						DESIGN	ED SN. KOBAYASHI	08. 1	2. 03		
						DRAW		1	2. 03		
Note QT:Qualification Test AT:Assurance Test X:App			urance Test X:Applicable Test	oplicable Test D		IG NO.	ELC4-081823	ELC4-081823-01			
HS.	SI	SPECIFICATION SHEET			PART NO.		DF13-10P-1. 25DS (50)				
		HIROSE ELECTRIC CO., LTD.			CODE NO.		536-0159-9-50	Δ	1/1		
EUDM HDUUTT	0 1										